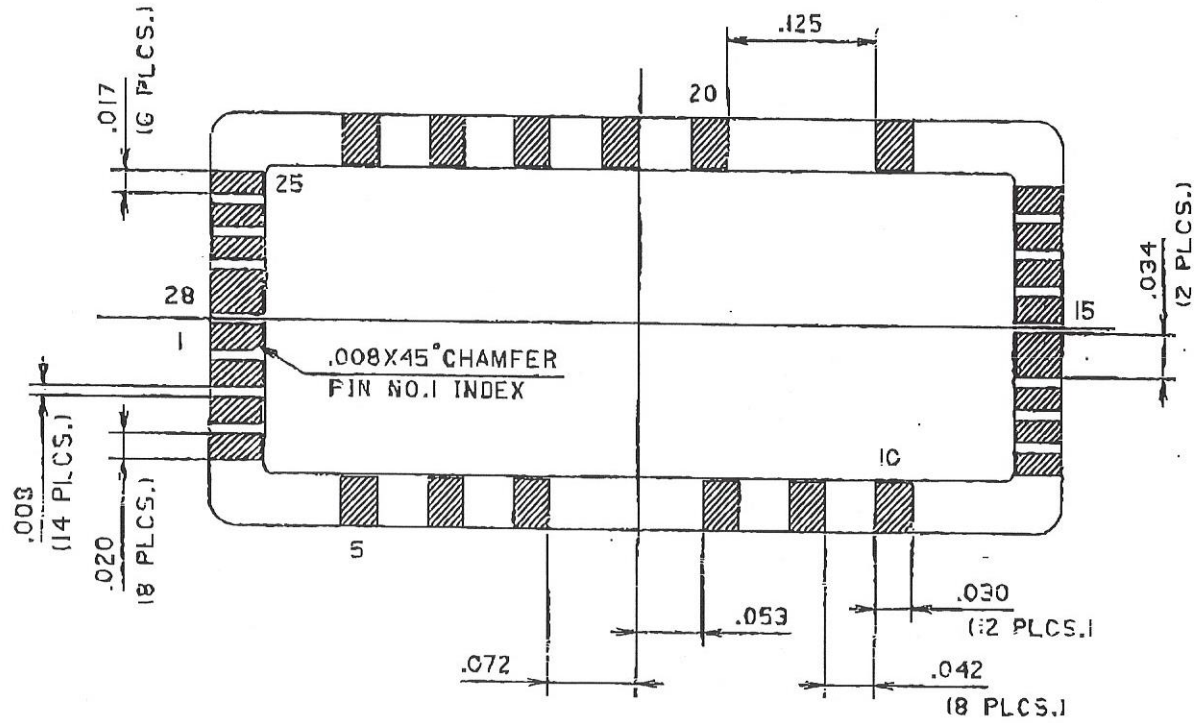


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.35 Ω MAX.

MODIFICATION					NAME 28 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005	DRAWN S.F	CHECKED S.T	APPROVED T.A	DATE NOV 20 '88	SBO28W866-1 5-3
					SCALE 4 / 1	MATERIAL AS INDICATED					
	CHANGED										

03/27/88
 27/11/88
 PHOENIX
 KYOCERA
 12/12/88

KYOCERA
 KYOCERA CORPORATION
 KYOTO JAPAN
 DRAWING NO.
 KD-589866
 SHEET
 1/2



BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					28 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F.	S.T.	M.K.	NOV. 20, 89
					SCALE 10/1	MATERIAL				
						KYOCERA CORPORATION KYOTO JAPAN				
	CHANGED				DATE FORAWN	CHECKED	APPROVED			DRAWING NO. KD-589866
										SHEET 3/3